



Serial No.: 09/943,763

**VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE**

What is claimed is:

1. (Amended) An assembly method for a semiconductor device assembly using a wire bonding device having an upper clamp member and a lower clamp member, said method comprising:  
forming a strip of lead frames, said strip having opposed rails, having dam bars between said opposed rails, having at least two inner leads, having at least two outer leads, having a die mount paddle and having at least one integral clamping tab, said at least one integral clamping tab extending outwardly for contact by said upper clamp member;  
attaching a semiconductor device to said die mount paddle, said semiconductor device having a plurality of bond pads;  
aligning said strip of lead frames on said lower clamp member of said wire bonding [apparatus]device having said upper clamp member overlying portions of said at least two inner leads and portions of said at least two outer leads of said at least one integral clamping tab; and  
attaching at least two bond wires to said plurality of bond pads of said semiconductor device and said portions of said at least two inner leads.
2. (Amended) The method of claim 1, further comprising[ the steps of]:  
forming said die mount paddle having [the]an upper surface thereof at a level below an upper level of said at least two inner leads; and  
deforming said at least one integral clamping tab to clamp portions thereof.
3. (Amended) The method of claim 1, further comprising[ the steps of]:  
removing said strip [pf]of lead frames and said semiconductor device from said lower clamp member; and

**Serial No.: 09/943,763**

encapsulating a portion of said strip of lead frames, said semiconductor [die]device, and said [plurality of]at least two bond wires extending between said strip of lead frames and said semiconductor device in a material.

**Serial No.: 09/943,763**

**IN THE DRAWINGS:**

Accompanying this Preliminary Amendment is a Letter to the Chief Draftsman submitting proposed revisions to FIGS. 3-5. Approval of the revised figures is respectfully requested. Also enclosed is a Transmittal of Formal Drawings with formal drawings revised as proposed.

**REMARKS**

No new matter has been added. The Applicant again requests entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



James R. Duzan  
Registration No. 28,393  
Attorney for Applicant  
TRASKBRITT  
P. O. Box 2550  
Salt Lake City, Utah 84110-2550  
Telephone: (801) 532-1922

Date: November 21, 2001

JRD/dn/blh  
N:\2269\3388.6\PRELIM.AMD

Enclosures:   Version of Specification with Markings to Show Changes Made  
                  Version of Claims with Markings to Show Changes Made